TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

| **PCN Number:** | **20260709000.1** | **PCN Issued** | July 09, 2026 |
|---|---|---|---|
| Qualification of RFAB as an additional Fab site, Die Revision, Datasheet and BOM options for select devices | | **Sample request deadline:** | September 07, 2026 |
| | | **Estimated 1st ship date:** | October 07, 2026 |
| ***Sample requests received after** September 07, 2026*** will not be supported.** | | | |

| **Change type(s)** |
|---|
| Assembly Material |
| Packing/Shipping/Labeling |
| Design |
| Data Sheet/Electrical Specification |
| Wafer Fab Site |
| Wafer Fab Material |
| Wafer Fab Process |

## *PCN Details*

### Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site, Die Revision, Datasheet & BOM options for the devices listed below.

| Current Fab Site | | | Additional Fab Site | | |
|---|---|---|---|---|---|
| **Current Fab Site** | **Process** | **Wafer Diameter** | **Additional Fab Site** | **Process** | **Wafer Diameter** |
| FFAB | ASLC10 | 200mm | RFAB | LBC9 | 300mm |

The die was also changed as a result of the process change.

Construction Differences are as follows:

| | **Current** | **Additional** |
|---|---|---|
| Wire diam/type | 0.96mil Cu | 0.8mil Cu |

### Data sheet update

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.

**Changes from July 1, 2014 to June 25, 2026 (from Revision L (July 2014) to Revision M (June 2026))** **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document ..... 1
- Moved ESD ratings to *ESD Ratings* table..... 1
- Updated latch-up ratings to latest standards..... 1
- Updated *Device Information* format and included package size..... 1
- Updated *Simplified Schematic* ..... 1
- Updated *Applications* ..... 1
- Added DGS and RKS package information..... 1
- Added DGS and RKS package information..... 2
- Added *ESD Ratings* table..... 4
- Changed Junction-to-ambient thermal resistance value for PW package from: 102.5°C/W to: 120.3°C/W ..... 5
- Changed Junction-to-case (top) thermal resistance value for PW package from: 35.9°C/W to: 62.5°C/W..... 5
- Changed Junction-to-board thermal resistance value for PW package from: 53.5°C/W to: 82.4°C/W..... 5
- Changed Junction-to-top characterization value for PW package from: 2.2°C/W to: 16.0°C/W..... 5
- Changed Junction-to-board characterization value for PW package from: 52.9°C/W to: 81.5°C/W..... 5
- Added DW, DB and NS package Thermal Information table..... 5
- Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately"..... 13
- Updated *Detailed Description*, *Application and Implementation* and *Device Documentation* sections..... 15



**Changes from June 1, 2014 to June 17, 2026 (from Revision N (June 2014) to Revision O (June 2026))** **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document..... 1
- Moved ESD ratings to *ESD Ratings* table..... 1
- Updated latch-up ratings to latest standards..... 1
- Updated *Device Information* format and included package size..... 1
- Updated *Simplified Schematic* ..... 1
- Updated *Applications* ..... 1
- Added DGS and RKS package information..... 1
- Changed RθJA for DB package from: 112.1°C/W to: 121.7°C/W..... 6
- Changed RθJC(top) for DB package from: 73.6°C/W to: 86.8°C/W..... 6

- Changed ΨJT for DB package from: 67.3°C/W to: 87.8°C/W ..... 6
- Changed ΨJB for DB package from: 33.3°C/W to: 44.7°C/W ..... 6
- Changed RθJC(bot) for DB package from: 66.9°C/W to: 87°C/W ..... 6
- Changed RθJA for DW package from: 99.4°C/W to: 114.8°C/W ..... 6
- Changed RθJC(top) for DW package from: 66.9°C/W to: 84.1°C/W ..... 6
- Changed ΨJT for DW package from: 66.9°C/W to: 88.8°C/W ..... 6
- Changed ΨJB for DW package from: 33.8°C/W to: 55.8°C/W ..... 6
- Changed RθJC(bot) for DW package from: 66.5°C/W to: 87.8°C/W ..... 6
- Changed RθJA for NS package from: 90.3°C/W to: 116.3°C/W ..... 6
- Changed RθJC(top) for NS package from: 56.6°C/W to: 82.4°C/W ..... 6
- Changed ΨJT for NS package from: 57.8°C/W to: 86.2°C/W ..... 6
- Changed ΨJB for NS package from: 28.7°C/W to: 43.9°C/W ..... 6
- Changed RθJC(bot) for NS package from: 57.4°C/W to: 85.5°C/W ..... 6
- Changed RθJA for PW package from: 100.8°C/W to: 120.3°C/W ..... 6
- Changed RθJC(top) for PW package from: 35.2°C/W to: 62.5°C/W ..... 6
- Changed ΨJT for PW package from: 51.8°C/W to: 82.4°C/W ..... 6
- Changed ΨJB for PW package from: 2.2°C/W to: 16°C/W ..... 6
- Changed RθJC(bot) for PW package from: 51.2°C/W to: 81.5°C/W ..... 6
- Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately" ..... 14



**Changes from May 1, 2014 to June 25, 2026 (from Revision N (May 2014) to Revision O (June 2026))** **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document ..... 1
- Moved ESD ratings to *ESD Ratings* table ..... 1
- Updated latch-up ratings to latest standards ..... 1
- Deleted military disclaimers ..... 1
- Updated *Device Information* format and included package size ..... 1
- Updated *Simplified Schematic* ..... 1
- Updated *Applications* ..... 1
- Added DGS and RKS package information ..... 1
- Added DGS and RKS packages to *Thermal Information* table ..... 5
- Changed RθJA for DW package from: 88.3°C/W to: 114.8°C/W ..... 5
- Changed RθJC(top) for DW package from: 51.1°C/W to: 84.1°C/W ..... 5
- Changed ΨJT for DW package from: 50.9°C/W to: 88.8°C/W ..... 5
- Changed ΨJB for DW package from: 20°C/W to: 55.8°C/W ..... 5
- Changed RθJC(bot) for DW package from: 50.5°C/W to: 87.8°C/W ..... 5
- Changed RθJA for PW package from: 102.5°C/W to: 120.3°C/W ..... 5
- Changed RθJC(top) for PW package from: 35.9°C/W to: 62.5°C/W ..... 5
- Changed ΨJT for PW package from: 53.5°C/W to: 82.4°C/W ..... 5
- Changed ΨJB for PW package from: 2.2°C/W to: 16°C/W ..... 5
- Changed RθJC(bot) for PW package from: 52.9°C/W to: 81.5°C/W ..... 5
- Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately" ..... 13

**Changes from February 2, 2026 to June 26, 2026 (from Revision AF (February 2026) to Revision AG (June 2026))** **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document..... 1
- Changed RθJA for DB package from: 108.1°C/W to: 121.7°C/W..... 6
- Changed RθJC(top) for DB package from: 70.2°C/W to: 86.8°C/W..... 6
- Changed ΨJT for DB package from: 63.3°C/W to: 87.8°C/W..... 6
- Changed ΨJB for DB package from: 30.6°C/W to: 44.7°C/W..... 6
- Changed RθJA for DW package from: 90.9°C/W to: 114.8°C/W..... 6
- Changed RθJC(top) for DW package from: 55.3°C/W to: 84.1°C/W..... 6
- Changed ΨJT for DW package from: 58.8°C/W to: 88.8°C/W..... 6
- Changed ΨJB for DW package from: 29.1°C/W to: 55.8°C/W..... 6
- Changed RθJA for NS package from: 90.1°C/W to: 116.3°C/W..... 6
- Changed RθJC(top) for NS package from: 56.4°C/W to: 82.4°C/W..... 6
- Changed ΨJT for NS package from: 57.7°C/W to: 86.2°C/W..... 6
- Changed ΨJB for NS package from: 28.4°C/W to: 43.9°C/W..... 6
- Changed RθJA for PW package from: 114.7°C/W to: 120.3°C/W..... 6
- Changed RθJC(top) for PW package from: 48.4°C/W to: 62.5°C/W..... 6
- Changed ΨJT for PW package from: 65.6°C/W to: 82.4°C/W..... 6
- Changed ΨJB for PW package from: 6.8°C/W to: 16°C/W..... 6
- Changed RθJA for RGY package from: 50.3°C/W to: 82.84°C/W..... 6
- Changed RθJC(top) for RGY package from: 58.4°C/W to: 88.73°C/W..... 6
- Changed ΨJT for RGY package from: 28.3°C/W to: 56.81°C/W..... 6
- Changed ΨJB for RGY package from: 4.9°C/W to: 32.37°C/W..... 6
- Changed RθJC(bot) for RGY package from: 28.4°C/W to: 56.62°C/W..... 6



**Changes from April 1, 2005 to June 24, 2026 (from Revision H (April 2005) to Revision I (June 2026))** **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document..... 1
- Moved ESD ratings to *ESD Ratings* table..... 1
- Updated latch-up ratings to latest standards..... 1
- Changed RθJA for DW package from: 58°C/W to: 114.8°C/W..... 5
- Changed RθJA for NS package from: 60°C/W to: 116.3°C/W..... 5
- Changed RθJA for PW package from: 83°C/W to: 120.3°C/W..... 5
- Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately"..... 14

**Changes from October 1, 2014 to June 1, 2026 (from Revision I (October 2014) to Revision J (June 2026))** — **Page**

- Add RKS package options ..... 1
- Moved $T_{stg}$ to *Absolute Maximum Ratings* table ..... 4
- Change *Handling Ratings* to *ESD Ratings* ..... 4
- Changed Junction-to-ambient thermal resistance value for PW package from: 103.5°C/W to: 120.3°C/W ..... 5
- Changed Junction-to-case (top) thermal resistance value for PW package from: 37.9°C/W to: 62.5°C/W ..... 5
- Changed Junction-to-board characterization value for PW package from: 54.5°C/W to: 82.4°C/W ..... 5
- Changed Junction-to-top characterization value for PW package from: 3.3°C/W to: 16°C/W ..... 5
- Changed Junction-to-board characterization value for PW package from: 53.9°C/W to: 81.5°C/W ..... 5
- Updated *Overview*, *Application and Implementation*, *Device and Documentation Support* sections to extend detailed feature descriptions and more detailed information. ..... 7
- Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately" ..... 12

| Product Folder | Current Datasheet Number | New Datasheet Number | Link to full datasheet |
|---|---|---|---|
| SN74LVC240A | SCAS293L | SCAS293M | http://www.ti.com/product/SN74LVC240A |
| SNx4LVC541A | SCAS298N | SCAS298O | http://www.ti.com/product/SN54LVC541A |
| SN74LVC540A | SCAS297N | SCAS297O | http://www.ti.com/product/SN74LVC540A |
| SN74LVC244A | SCAS414AF | SCAS414AG | http://www.ti.com/product/SN74LVC244A |
| SN74LVCZ240A | SCES273H | SCES273I | http://www.ti.com/product/SN74LVCZ240A |
| SN74LVCZ244A | SCES274I | SCES274J | http://www.ti.com/product/SN74LVCZ244A |

Qual details are provided in the Qual Data Section.

| | |
|---|---|
| **Reason for Change:** | Supply Continuity |

| | |
|---|---|
| **Anticipated impact on Form, Fit, Function, Quality or Reliability:** | Physical aspects of the device have changed. Review updated datasheets and/or the Standard Data Packet for more details on the changes |
| **Impact on Environmental Ratings** | Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings. |

| RoHS | REACH | Green Status | IEC 62474 |
|---|---|---|---|
| ☒ No Change | ☒ No Change | ☒ No Change | ☒ No Change |

**Changes to product identification resulting from this PCN:**

**Fab Site Information**

| Chip Site | Chip Site Origin Code (20L) | Chip Site Country Code (21L) | Chip Site City |
|---|---|---|---|
| FFAB | TID | DEU | Freising |
| **RFAB** | **RFB** | **USA** | **Richardson** |

## Die Rev:

| Current | New |
|---|---|
| Die Rev [2P] | **Die Rev [2P]** |
| A, E, P | **A** |

Sample product shipping label (not actual product label):


## Products Affected:

| | | |
|---|---|---|
| SN74LVC240ADWR | SN74LVC244ADWRG4 | SN74LVC541ADBR |
| SN74LVC244ADBR | SN74LVC244ADWRE4 | SN74LVC541ADBRG4 |
| SN74LVC244ADBRE4 | SN74LVC244ANSR | SN74LVC541ADWR |
| SN74LVC244ADBRG4 | SN74LVC244ANSRG4 | SN74LVC541ADWRE4 |
| SN74LVC244ADWR | SN74LVC540ADWR | SN74LVC541ANSR |

# Qualification Report
## FAB5 LD4 PCN 20 NS
Approve Date 03-November -2025

## Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

| Type | # | Test Name | Condition | Duration | Qual Device: SN74LVC244ANSR | Qual Device: SN74LVC541ANSR | Process QBS Reference: SN74HCS74QPWRQ1 | Package QBS Reference: SN74LVC8T245NSR | Package QBS Reference: SN74LV244AQDGSRQ1 | Package QBS Reference: SN74LV273AQDGSRQ1 | Package QBS Reference: SN74LV541AQDGSRQ1 | Product QBS Reference: SN74LVC9541APWRQ1 | Process QBS Reference: SN74LVC240APWRQ1 |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| HAST | A2 | Biased HAST | 130C/85%RH | 96 Hours | - | - | 3/231/0 | - | 1/77/0 | 1/77/0 | 1/77/0 | - | 1/77/0 |
| UHAST | A3 | Autoclave | 121C/15psig | 96 Hours | - | - | 3/231/0 | - | 1/77/0 | 1/77/0 | 1/77/0 | - | - |
| TC | A4 | Temperature Cycle | -65C/150C | 500 Cycles | - | - | 3/231/0 | 3/231/0 | 1/77/0 | 1/77/0 | 1/77/0 | - | 1/77/0 |
| HTSL | A6 | High Temperature Storage Life | 150C | 1000 Hours | - | - | 3/135/0 | 3/231/0 | 1/45/0 | 1/45/0 | 1/45/0 | - | - |
| HTOL | B1 | Life Test | 125C | 1000 Hours | - | - | 3/231/0 | - | 1/77/0 | - | - | - | - |
| HTOL | B1 | Life Test | 150C | 300 Hours | - | - | - | - | - | - | - | - | 1/77/0 |
| ELFR | B2 | Early Life Failure Rate | 125C | 48 Hours | - | - | 3/2400/0 | - | - | - | - | - | - |
| SD | C3 | PB Solderability | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes) | - | - | - | 1/15/0 | - | 1/15/0 | - | - | - | - |
| SD | C3 | PB-Free Solderability | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes) | - | - | - | 1/15/0 | - | 1/15/0 | - | - | - | 1/15/0 |
| PD | C4 | Physical Dimensions | Cpk>1.67 | - | - | - | 3/30/0 | - | 1/10/0 | 1/10/0 | 1/10/0 | - | 1/10/0 |
| ESD | E2 | ESD CDM | - | 250 Volts | 1/3/0 | - | 1/3/0 | - | 1/3/0 | 1/3/0 | 1/3/0 | 1/3/0 | 1/3/0 |
| ESD | E2 | ESD HBM | - | 2000 Volts | - | - | 1/3/0 | - | 1/3/0 | 1/3/0 | 1/3/0 | 1/3/0 | 1/3/0 |
| LU | E4 | Latch-Up | Per JESD78 | - | - | - | 1/6/0 | - | 1/6/0 | 1/6/0 | 1/6/0 | 1/3/0 | 1/3/0 |
| CHAR | E5 | Electrical Characterization | Per Datasheet Parameters | - | 1/30/0 | 1/30/0 | 3/90/0 | - | 1/30/0 | 1/30/0 | 1/30/0 | 1/30/0 | 1/30/0 |

QBS: Qual By Similarity, also known as Generic Data
Qual Device SN74LVC244ANSR is qualified at MSL1 260C
Qual Device SN74LVC541ANSR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site:
http://www.ti.com/

TI Qualification ID: R-CHG-2409-092

# Qualification Report
## FAB5 LD4 PCN 20 DB
Approve Date 19-November-2025

## Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

| Type | # | Test Name | Condition | Duration | Qual Device: SN74LVC244ADBR | Qual Device: SN74LVC541ADBR | Package QBS Reference: SN74HCS74QPWRQ1 | Package QBS Reference: SN74LV244AQDGSRQ1 | Package QBS Reference: SN74LV273AQDGSRQ1 | Package QBS Reference: SN74LV541AQDGSRQ1 | Process QBS Reference: GD75232DBR | Process QBS Reference: SN74LVC9541APWRQ1 | Product QBS Reference: SN74LVCZ240APWRQ1 |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| HAST | A2 | Biased HAST | 130C/85%RH | 96 Hours | - | - | 3/231/0 | 1/77/0 | 1/77/0 | 1/77/0 | 1/77/0 | - | 1/77/0 |
| UHAST | A3 | Autoclave | 121C/15psig | 96 Hours | - | - | 3/231/0 | 1/77/0 | 1/77/0 | 1/77/0 | - | - | - |
| UHAST | A3 | Unbiased HAST | 130C/85%RH | 96 Hours | - | - | - | - | - | - | 1/77/0 | - | 1/77/0 |
| TC | A4 | Temperature Cycle | -65C/150C | 500 Cycles | - | - | 3/231/0 | 1/77/0 | 1/77/0 | 1/77/0 | 1/77/0 | - | 1/77/0 |
| HTSL | A6 | High Temperature Storage Life | 150C | 1000 Hours | - | - | 3/135/0 | 1/45/0 | 1/45/0 | 1/45/0 | 1/77/0 | - | - |
| HTSL | A6 | High Temperature Storage Life | 175C | 500 Hours | - | - | - | - | - | - | - | - | 1/45/0 |
| HTOL | B1 | Life Test | 125C | 1000 Hours | - | - | 3/231/0 | 1/77/0 | - | - | - | - | - |
| HTOL | B1 | Life Test | 150C | 300 Hours | - | - | - | - | - | - | - | - | 1/77/0 |
| SD | C3 | PB Solderability | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes) | - | - | - | 1/15/0 | 1/15/0 | - | - | - | - | - |
| SD | C3 | PB-Free Solderability | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes) | - | - | - | 1/15/0 | 1/15/0 | - | - | - | - | 1/15/0 |
| PD | C4 | Physical Dimensions | Cpk>1.67 | - | - | - | 3/30/0 | 1/10/0 | 1/10/0 | 1/10/0 | - | - | 1/10/0 |
| ESD | E2 | ESD CDM | - | 250 Volts | 1/3/0 | - | 1/3/0 | 1/3/0 | 1/3/0 | 1/3/0 | 1/3/0 | 1/3/0 | 1/3/0 |
| ESD | E2 | ESD HBM | - | 1000 Volts | - | - | 1/3/0 | 1/3/0 | 1/3/0 | 1/3/0 | - | 1/3/0 | 1/3/0 |
| LU | E4 | Latch-Up | Per JESD78 | - | - | - | 1/6/0 | 1/6/0 | 1/6/0 | 1/6/0 | - | 1/3/0 | 1/3/0 |
| CHAR | E5 | Electrical Characterization | Per Datasheet Parameters | - | 1/30/0 | 1/30/0 | 3/90/0 | 1/30/0 | 1/30/0 | 1/30/0 | - | 1/30/0 | 1/30/0 |

QBS: Qual By Similarity, also known as Generic Data
Qual Device SN74LVC244ADBR is qualified at MSL1 260C
Qual Device SN74LVC541ADBR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2503-036

# Qualification Report
## FAB5 LD4 PCN 20 DW
Approve Date 19-November-2025

## Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

| Type | # | Test Name | Condition | Duration | Qual Device: SN74LVC240ADWR | Qual Device: SN74LVC244ADWR | Package QBS Reference: SN74HCS74QPWRQ1 | Package QBS Reference: SN74AHC244QDWRG4 | Process/Product QBS Reference: SN74LS245DWR | Process QBS Reference: SN74LVC240APWRQ1 |
|---|---|---|---|---|---|---|---|---|---|---|
| HAST | A2 | Biased HAST | 130C/85%RH | 96 Hours | - | - | 3/231/0 | 1/77/0 | 3/231/0 | 1/77/0 |
| UHAST | A3 | Autoclave | 121C/15psig | 96 Hours | - | - | 3/231/0 | - | - | - |
| UHAST | A3 | Unbiased HAST | 130C/85%RH | 96 Hours | - | - | - | 1/77/0 | 3/231/0 | 1/77/0 |
| TC | A4 | Temperature Cycle | -65C/150C | 500 Cycles | - | - | 3/231/0 | 1/77/0 | 3/231/0 | 1/77/0 |
| HTSL | A6 | High Temperature Storage Life | 150C | 1000 Hours | - | - | 3/135/0 | 1/45/0 | 3/231/0 | - |
| HTOL | B1 | Life Test | 150C | 300 Hours | - | - | - | 1/77/0 | - | 1/77/0 |
| ELFR | B2 | Early Life Failure Rate | 125C | 48 Hours | - | - | 3/2400/0 | - | - | - |
| SD | C3 | PB Solderability | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes) | - | - | - | 1/15/0 | - | - | - |
| SD | C3 | PB-Free Solderability | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes) | - | - | - | 1/15/0 | 1/15/0 | - | 1/15/0 |
| PD | C4 | Physical Dimensions | (per mechanical drawing) | - | - | - | - | 2/10/0 | - | - |
| PD | C4 | Physical Dimensions | Cpk>1.67 | - | - | - | 3/30/0 | 1/10/0 | - | 1/10/0 |
| ESD | E2 | ESD CDM | - | 250 Volts | - | 1/3/0 | 1/3/0 | 1/3/0 | 1/3/0 | 1/3/0 |
| ESD | E2 | ESD HBM | - | 1000 Volts | - | - | 1/3/0 | 1/3/0 | 1/3/0 | 1/3/0 |
| LU | E4 | Latch-Up | Per JESD78 | - | - | - | 1/6/0 | 1/3/0 | 1/3/0 | 1/3/0 |
| CHAR | E5 | Electrical Characterization | Per Datasheet Parameters | - | 1/30/0 | 1/30/0 | 3/90/0 | 1/30/0 | 1/30/0 | 1/30/0 |

QBS: Qual By Similarity, also known as Generic Data
Qual Device SN74LVC240ADWR is qualified at MSL1 260C
Qual Device SN74LVC244ADWR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2503-035

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also

known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.